

## WEST Search History

DATE: Monday, June 13, 2005

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<i>DB=USPT; PLUR=YES; OP=ADJ</i>			
<input checked="" type="checkbox"/>	L10	L8 and glass	3
<input checked="" type="checkbox"/>	L9	L8 and lcd	0
<input checked="" type="checkbox"/>	L8	6202658	7
<input checked="" type="checkbox"/>	L7	L6 and (brush with edge)	12
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<input checked="" type="checkbox"/>	L4	(4935981  5282289  5351360  5485644  5547415  5868866  6059891  6158075  6286525  6292972)!*[pn]	10
<input checked="" type="checkbox"/>	L3	L2 and (134/\$.ccls. or 15/\$.ccls.)	26
<input checked="" type="checkbox"/>	L2	L1 and (side surface)	94
<input checked="" type="checkbox"/>	L1	lcd and brush	1203

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L11: Entry 1 of 1

File: DWPI

Nov 11, 2003

DERWENT-ACC-NO: 2001-175110

DERWENT-WEEK: 200382

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TITLE: Semiconductor substrate washing apparatus has oscillator to oscillate scrub cleaning unit with cleaning tool and liquid gel cleaning unit which injects liquid through nozzle, simultaneously to clean wafer surface

INVENTOR: ATOH, K; INOUE, T ; INOUE, Y ; SOTOZAKI, H

PATENT-ASSIGNEE:

ASSIGNEE	CODE
EBARA CORP	EBAR

PRIORITY-DATA: 1999JP-0171223 (June 17, 1999)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input checked="" type="checkbox"/> <a href="#">US 6643882 B1</a>	November 11, 2003		000	B08B001/04
<input checked="" type="checkbox"/> <a href="#">JP 2001007069 A</a>	January 12, 2001		012	H01L021/304

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
US 6643882B1	June 16, 2000	2000US-0594787	
JP2001007069A	June 17, 1999	1999JP-0171223	

INT-CL (IPC): B08 B 1/04; H01 L 21/304

ABSTRACTED-PUB-NO: JP2001007069A

BASIC-ABSTRACT:

NOVELTY - A scrub cleaning unit (10) has cleaning tool (15) which is made to contact wafer (W). Liquid jet cleaning unit (30) injects cleaning liquid through nozzle (31) to clean the wafer. An oscillator (50) oscillates both the cleaning units simultaneously and cleaning tool is vertically moved by drive unit (17). Movement of both the units enables uniform cleaning of wafer surface.

USE - For cleaning substrates like semiconductor wafer, LCD substrate.

ADVANTAGE - As cleaning unit and liquid jet cleaning unit are simultaneously used, cleaning time is shortened and efficiency is increased. The structure and control

are simplified as no special installation for self-cleaning is required.

DESCRIPTION OF DRAWING(S) - The figure shows the schematic block diagram of semiconductor substrate washing apparatus.

Scrub cleaning unit 10

Cleaning tool 15

Drive unit 17

Liquid jet cleaning unit 30

Nozzle 31

Oscillator 50

Wafer W

CHOSEN-DRAWING: Dwg.1/15

TITLE-TERMS: SEMICONDUCTOR SUBSTRATE WASHING APPARATUS OSCILLATOR OSCILLATING SCRUB CLEAN UNIT CLEAN TOOL LIQUID GEL CLEAN UNIT INJECTION LIQUID THROUGH NOZZLE SIMULTANEOUS CLEAN WAFER SURFACE

DERWENT-CLASS: P43 U11

EPI-CODES: U11-C06A1B;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N2001-126992

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